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# AMENDMENT TRANSMITTAL LETTER

Docket No. TESSERA 3.0-070 DIV

Application No. 09/779,117

Filing Date February 8, 2001

Examiner Tuan Dinh Art Unit 2827

Applicant(s): Thomas H. DiStefano and Joseph Fjelstad

## **ELECTRICAL CONNECTION WITH INWARDLY DEFORMABLE CONTACTS**

### TO THE COMMISSIONER FOR PATENTS

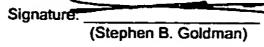
Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

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Independent Claims	3	- 3 =		x	0.00
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Stephen B. Gold Attorney Reg. N					, p
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Dated: April 3, 2003



Docket No.: TESSERA 3.0-070 DIV

(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

DiStefano et al

Application No.: 09/779,117 : Group Art Unit: 2827

Filed: February 8, 2001 : Examiner: Tuan Dinh

For: ELECTRICAL CONNECTION WITH INWARDLY DEFORMABLE CONTACTS

Commissioner for Patents Washington, DC 20231

#### AMENDMENT

Dear Sir:

Official In response the to Action mailed October 17, 2002, Applicants submit the following amendments and remarks.

#### IN THE CLAIMS

- 18. (AMENDED) An interposer as claimed in claim 17, wherein each said conductor extends substantially perpendicularly to said first major surface.
- 21. (AMENDED) An interposer for making connections to pads on the surface of a microelectronic element, said pads defining holes therein, comprising:
  - an interposer body having a first surface; and
- a plurality of contacts on said body, each said (b) contact comprising a central portion extending through said first surface into said body, and a peripheral portion extending